

Dual Interface Cards & Technologies



COMPANY



Introduction



- Owner-managed group
- International market leadership in the fields of
 - Parts & Systems
 - Semiconductor Related Products
 - Document Solution Related Products
 - TECURITY[®] Solutions
- The Mühlbauer Group's philosophy: Our customers are our partners!



Facts









BASIS

- 3,500 employees at 35 sites worldwide
- 400 engineers in R&D
- 400 trainees
- Excellent sustainability standards

BASIS

- Annual investments (approx. 15 million EUR) in
 - Latest technologies
 - Infrastructure
 - Systematical & logical completion of the product chain

MARKET POSITION

- PARTS & SYSTEMS parts manufacturing across all sectors
- AUTOMATION market leader in the areas of RFID
- TECURITY[®] solution partner for identification & verification projects

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International Sites



HQ Germany_ Production Center Bosnia-Herzegovina_

Production Center USA

Production Center Germany Production Center Slovakia Production Center Serbia

Production Center China_

Production Center Malaysia.

35 production & service locations

 Technology centers in the USA, Slovakia, Serbia, Malaysia & China

Inhouse precision-part production

Provision of

- High-end semiconductor & RFID systems

- Reliable vision inspection technologies

 Innovative ID document end-to-endsolutions

- Secure access & border control systems





TECURITY® Solutions for Governments



The Innovation Platform



SEMICONDUCTORS

Intelligence for Security & Communication



RFID

Smart Label Technology for TECURITY[®] & IOT



FLEXIBLE SOLAR

Efficient Solution for Clean Energy Everywhere



LED

Energy-Saving Light for the Future





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Security & Quality Certificates





10/8/2019

Constant"

Associations & Initiatives



MEMBERSHIP IN GOVERNMENTAL INITIATIVES, WORKING GROUPS & COMMITTEES

- German-African Business Association
- Ghorfa Arab-German Chamber of Commerce and Industry e.V.
- IATA Strategic Partner
- INTERPOL Project S-Print
- Operation Genesius
 U.S. Department of Homeland Security









This company supports the ICE initiative to prevent the sales of equipment for illegal purposes. Information may be shared with law enforcement.

ICE does not endorse the products or services of participating companies.











Mobile Payment Market



Mobile Payment Market / Global Comparison Transaction Value





Top 5				
🛅 China	US\$581,372m			
United States	US\$87,040m			
🔢 United Kingdom	US\$10,949m			
💽 Brazil	US\$6,297m			
💶 India	US\$5,975m			



Mobile POS Transaction Value in the US





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Mobile POS Transaction Users in the US





US Mobile POS Transaction Users by age



15



Average Transaction Value per User







In particular MB TeConnect

Dual Interface Technologies



Dual Interface Technologies / Overview



Electromagnetic Coupling	Electromagnetic coupling of the chip and the antenna	 + Low invest for integration in existing production Non-destructive manipulation Chip/Card possible Expensive consumables (Chip & Inlay) Dependency on specific antenna and chip module supplier Not capable for high power connections (BC or SoC) Card body and chip module need to be fine tuned 	
MB-TeConnect	Advanced Solder Technology	 + Solid and reliable physical connection + Certified for 10 years on PC + Ready for Pre- Personalization right away + Simple wire antenna with meander + Ideal Technology for Biometric or System on Card 	
Other Solder Technologies	Require additional metal pad and partially additional Pre-Solder on Device	 + Low invest for integration in existing production + Ready for Pre- Personalization right away - High cost due to additional tin or copper pad/Pre-Solder - Increased failure risk due add. interconnection wire & pad - Metal pads in card create deformation through processing 	
Anisotropic Conductive Film	Conductive HAF	 Low invest for integration in existing production High consumable cost Not working on standard wire antenna, metal pad required High failure rate in performance test (HAF takes humidity) Danger of warpage of card (unsymmetrical card structure) 	



MB TeConnect Technology \rightarrow Highest Quality Level

MB TC versus ISO Requirements



MB TeConnect already holds:

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High Tech International

MB TeConnect simple card construction





MB TeConnect simple 3 STEP Production

High Tech International MB-TeC 5000 INLINE PRODUCTION Chip module implanting Milling of Dispensing No curing **MB** TeConnect antennas time in process



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FACTS & FIGURES

- Real "INLINE" process enabling Pre-personalization as option
- Strongest Physical connection between antenna and chip
- Proven durability and reliability from external laboratories
- Inline Dual Interface production workflow
- MB-TeC 5000 paste is shipped as non hazardous substance

10/8/2019

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MB TeConnect > BE INDEPENDENT!



Feel free...

- ...to use what ever (Dual Interface) chip module you want.
- ...to use different antenna types; Recommended embedded copper wire antenna, but also etched antenna or wire with metal plates is possible.
- ...to use the inlay substrate material you want: PVC, PC, ABS., etc...
- ...to use your own antenna design.
- ...to use a proven 2nd generation Technology with best cost per Card Ratio for highly competitive business





Reject costs per year

(13m cards/year,0,80€ per card)



Cost of ownership per card: 0,018 €



MB TeConnect Cost advantage versus electromagnetic Coupling



MB TeConnect	Additional Consumbale Cost	Inductive Coupling	Yearly production	Cost saving	
\checkmark	Antenna Inlay	+ 0,04€/card	4.500.000 cards	400.500€	
\checkmark	Module	+ 0,05€/card	10.000.000 cards	890.000€	
+0,006€/card	Paste	\checkmark	13.000.000 cards	1.157.000€	
+0,005€/card	Milling Tool Antenna Touch	\checkmark	50.000.000 cards	4.450.000€	
\checkmark	Bonding/glue coating	+0,01€/card	100.000.000 cards	8.900.000€	
+0,011€/card	Total	+0,10€/card			
- 0,089€/card	Advantage MB	+0,089€/card	Max. Output of 1 DICL5000 machine per year running 3 shifts		



Potential for Future

Biometric Card & System on Card

MB TeConnect



MB TeConnect capable for Biometric Card & similar Applications





Capable for multiple reliable connection points Ideal for mass/volume production Internal passed CQM requirements (3.000 bendings)

FPS Makers: Fingerprint Cards AB (2/2)

The Fingerprint Cards 7-Shape is a packaging option for the FPC 1300 series
Optimized for hot lamination - milling + embedding process



The Key of Sametric Lands (Instantial Security Wess) restantialization compared calls Salidar Inneres (2017) 27 (07) Annual Million, sur Parcip Maggari (Al annual security, spin, and hands of parcent, of finit regardle tensors,



MB TeConnect Worldwide References

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Reliable Partner



- Confidence of governments & public authorities worldwide
- Trust and reliability our most important values
- Convincing by high speed, best quality & strict customer orientation
- Planning, risk management, effective monitoring & support
- Close partnerships with all stakeholders

YOUR TRUST IS OUR GREATEST MOTIVATION TO TURN EVERY CHALLENGE INTO A SUCCESS STORY.



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